



ELECTRONICS DESIGN & MANUFACTURING SOLUTIONS

- Vertically integrated to provide design, development, manufacturing and testing.
- Turnkey solutions for your production requirements.
- End-to-end supply chain management.
- Undivided attention to customers, bringing flexibility and focus to their needs.

DESIGN | PROTOTYPING | MANUFACTURING | LIFECYCLE MANAGEMENT

Design, Fabrication & Test Services

Hi-rel Qualified Processes and Technologies

- Thermocompression Bonding
- Thermosonic / Ultrasonic Bonding
- Micro-resistance Spot Welding
- Epoxy And Adhesive Technologies
- Reflow/vacuum/vapour Soldering
- Precision Mechanical Assembly
- Surface Mount Technologies
- Composite Material Technologies
- Conformal Coatings and Potting

RF & Microwave Payload Subsystems Fabrication

- Low Noise Amplifiers
- 1GBPS X Band Payload Transmitter
- Frequency Converters
- Frequency Generators
- Receivers
- Payload Antenna
- Medium & High gain Driver/Power Amplifiers
- TM/TC module
- Power Combiners/Dividers
- Passive Microwave Components & Systems
- VHF/UHF/I/s/c/x/ka/ku Band SDR
- High & Low power Waveguide Filters/Couplers/Circulators/Isolators/Diplexers/OMUX/OMUX

Design, Fabrication & Test Services

Hi-rel Fabrication, Assembly and Testing

- Alumina, Duroid, Ltcc, Assembly
- Dry Etching Laser Lithography
- Wire Bonding (MMIC, MIC, CMOS)
- Precision Die Bonding (Face Up)
- Flip Chip Bonding (Face Down)
- BGA, CCGA, PGA, QFP, Fine-pitch Assembly
- Fully Automated Through-hole using Selective Soldering
- Fully Automated SMT Assembly
- Multi Chip Packaging (MCM, MCP)
- Micro-optical Package Assembly
- DC / RF Semi-rigid/ Flex Cables
- Automatic Optical Inspection
- X-Ray Analysis



Space Grade Testing

- Climatic Test Facility
- EMI/EMC Test Facility
- Electrostatic Discharge
- Environmental Stress Screening
- Sine & Random Vibration Facility (1 ton, 2.5 ton & 6 ton)
- Mechanical Shock Test Facility
- Thermal Vacuum Testing
- Highly Accelerated Thermal Shock Test (HATS) Facility
- Helmholtz Testing
- Fully Automated RF Test Bench (1-40GHz)



Note: Your one-stop partner for Hi-Rel Electronics Design & Manufacturing Services (EDMS), offering seamless solutions for Built to Print (BTP) and Built to Spec (BTS) projects.

Infrastructure and Capabilities

- Class-10000 Clean rooms for MMIC/MIC/PFF assemblies
- ESD-safe Electronic Assembly facility with Automated SMT lines and robotic Selective soldering for PTH
- 12-zone SMT Reflow ovens in wholly conveyORIZED lines, capable of handling multi-layer PCBs
- In-line Automatic Optical Inspection system
- BGA Assembly and rework capabilities, along with 2.5D X-Ray system
- Advanced test facilities for RF Test, Customized Functional test etc.
- HASS/Reliability testing based on ESS, Temperature Cycling and Vibration Test capabilities
- Anechoic chamber¹ for EMI/EMC testing
- Conformal Coating using both Automated and Manual process
- HATS testing for bare PCBs

(¹ NABL Accreditation in process)



Standards & Certifications



ISO13485 Under Process



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